

BMR-C1

ENZOTECH BMR-C1 RAM sinks are designed to offer exceptional heat dissipation for BGA memory chips on video cards and motherboards. BMR-C1 RAM sinks are made using a forged copper process which produces a dense material that is extremely efficient at heat extraction. The BMR-C1 RAM sink is far superior to traditional heat sinks currently found on the market and provides the best thermal conductivity available to dissipate heat from RAM in your system.

Features

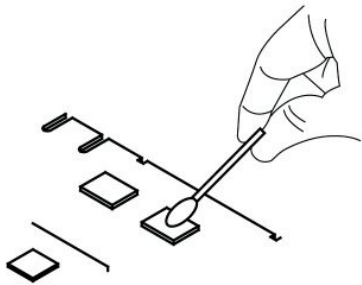
- ATI& NVIDIA Compatible
- Forged pure copper
- Easy installation with thermal tape

Specifications

- Dimensions: 14mm(L) x 14mm(W) x 14mm(H)
- Weight: 7g (each)
- Material: Forged Copper 1100
- Thermal Adhesive: 3M #8815 Thermal Tape

Installation

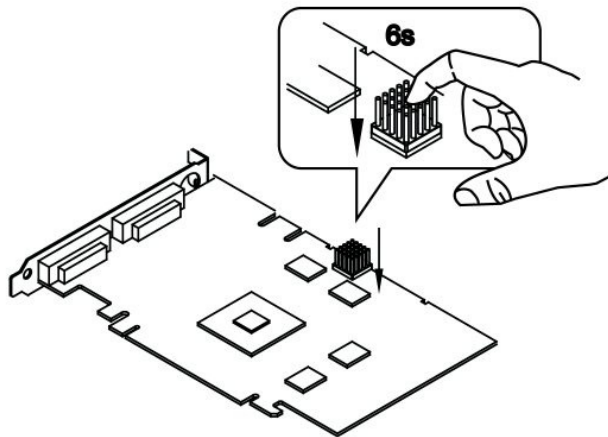
- 1 Carefully clean the surface of the BGA modules with the degreaser
*Recommend cleaner: Arctic Clean 1&2



- 2 Remove protective liner from the thermal pad on the base of the heat sink



- 3 Affix RAM sink to BGA module by applying firm pressure for at least six seconds



Caution<!>

The following situations can result in the RAM sink falling off the BGA chipset

- surface of the BGA module is not big enough (BGA module must be at least 14mm X 14 mm)
- BGA module surface was not properly cleaned prior to affixing RAM sink. Please make sure surface is properly cleaned prior to fixation of RAM sink.
- Thermal tapes cannot be reused. If the RAM sink must be removed, Do Not use same thermal tape to re-attach. Both surfaces must be completely cleaned and new thermal interface tape must be applied.
- When cleaning mating surfaces, be sure to follow directions supplied with cleaning product to insure safety for yourself and others.
- Do Not swallow and keep contents away from children.